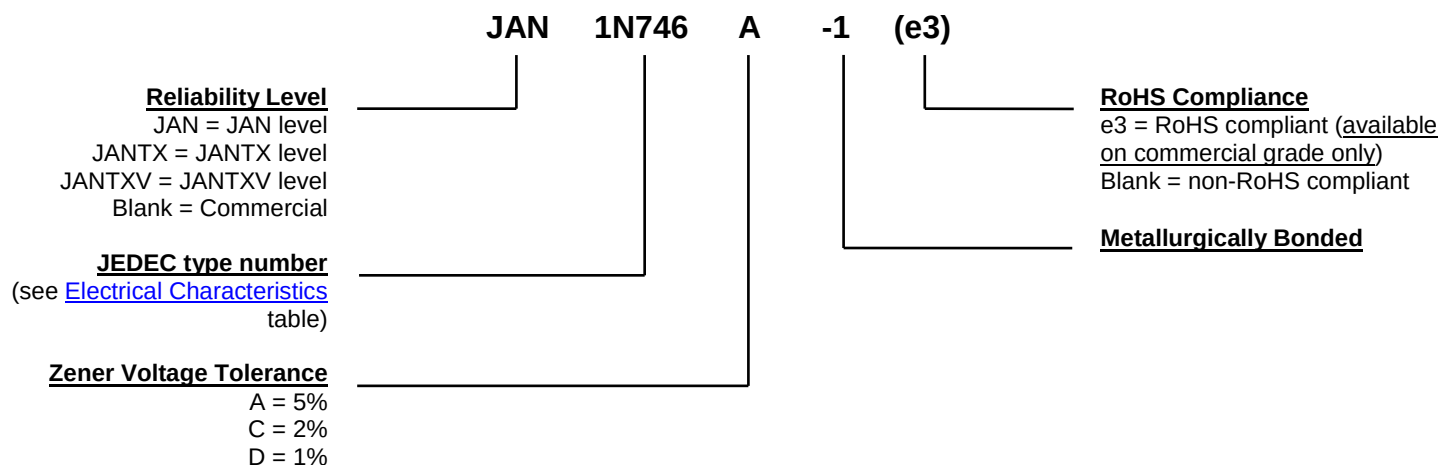


MECHANICAL and PACKAGING

- CASE: Hermetically sealed axial-lead glass DO-35 (DO-204 AH) package.
- TERMINALS: Tin-lead or RoHS compliant annealed matte-tin plating (on commercial grade only). Solderable per MIL-STD-750, method 2026.
- MARKING: Part number.
- POLARITY: Cathode indicated by band. Diode to be operated with the banded end positive with respect to the opposite end for Zener regulation.
- TAPE & REEL option: Standard per EIA-296 (add "TR" suffix to part number).
- WEIGHT: Approximately 0.2 grams
- See [Package Dimensions](#) on last page.

PART NOMENCLATURE



SYMBOLS & DEFINITIONS

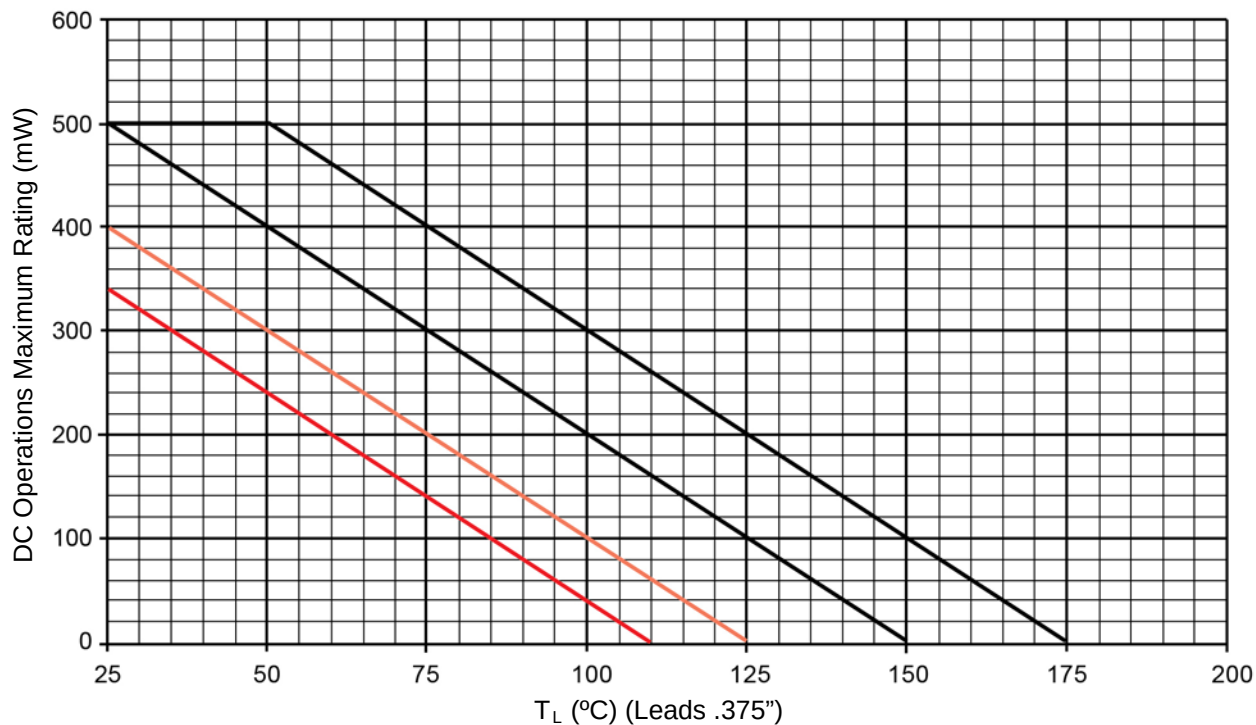
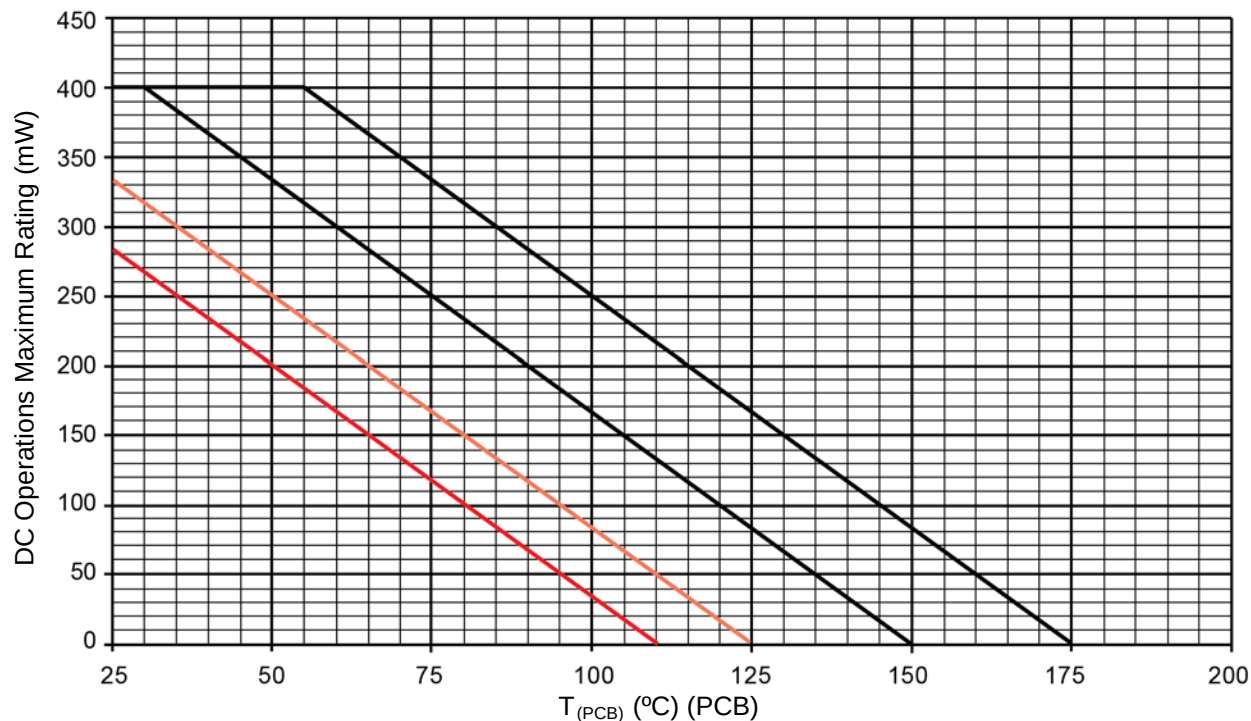
Symbol	Definition
I_R	Reverse Current: The maximum reverse (leakage) current that will flow at the specified voltage and temperature.
I_Z, I_{ZT}, I_{ZK}	Regulator Current: The dc regulator current (I_Z), at a specified test point (I_{ZT}), near breakdown knee (I_{ZK}).
I_{ZM}	Maximum Regulator (Zener) Current: The maximum rated dc current for the specified power rating.
I_{ZSM}	Maximum Zener Surge Current: The non-repetitive peak value of Zener surge current at a specified wave form.
V_F	Maximum Forward Voltage: The maximum forward voltage the device will exhibit at a specified current.
V_R	Reverse Voltage: The reverse voltage dc value, no alternating component.
V_Z	Zener Voltage: The Zener voltage the device will exhibit at a specified current (I_Z) in its breakdown region.
Z_{ZT} or Z_{ZK}	Dynamic Impedance: The small signal impedance of the diode when biased to operate in its breakdown region at a specified rms current modulation (typically 10% of I_{ZT} or I_{ZK}) and superimposed on I_{ZT} or I_{ZK} respectively.

ELECTRICAL CHARACTERISTICS @ 25 °C

JEDEC TYPE NO. (NOTE 1)	NOMINAL ZENER VOLTAGE $V_Z @ I_{ZT}$ (NOTE 2)	MAXIMUM ZENER IMPEDANCE $Z_{ZT} @ I_{ZT}$ (NOTE 3)	MAXIMUM REVERSE VOLTAGE V_R	MAXIMUM REVERSE CURRENT $I_R @ V_R$		MAXIMUM ZENER CURRENT I_{ZM} (NOTE 4)	TEMPERATURE COEFFICIENT OF ZENER VOLTAGE α_{VZ}
				@ 25 °C	@ +150 °C		
				μA	μA		
1N4370A-1	2.4	30	1.0	100	200	155	-0.085
1N4371A-1	2.7	30	1.0	60	150	140	-0.080
1N4372A-1	3.0	29	1.0	30	100	125	-0.075
1N746A-1	3.3	24	1.0	5	30	120	-0.070
1N747A-1	3.6	22	1.0	3	30	110	-0.065
1N748A-1	3.9	20	1.0	2	30	100	-0.060
1N749A-1	4.3	18	1.0	2	50	90	-0.055 / +.020
1N750A-1	4.7	15	1.5	5	50	85	-0.043 / +.025
1N751A-1	5.1	14	2.0	5	50	75	-0.030 / +.030
1N752A-1	5.6	8	2.5	5	50	70	-0.028 / +.036
1N753A-1	6.2	3	3.5	5	50	65	+0.045
1N754A-1	6.8	3	4.0	2	50	60	+0.050
1N755A-1	7.5	4	5.0	2	50	55	+0.058
1N756A-1	8.2	5	6.0	1	50	50	+0.062
1N757A-1	9.1	6	7.0	1	50	45	+0.068
1N758A-1	10.0	7	8.0	1	50	40	+0.076
1N759A-1	12.0	10	9.0	1	50	35	+0.080

NOTES:

1. The JEDEC type numbers shown (A suffix) have a $\pm 5\%$ tolerance on nominal Zener voltage.
2. Voltage measurements to be performed 20 seconds after application of dc test current.
3. Zener impedance derived by superimposing on I_{ZT} , a 60 cps, rms current equal to 10% I_{ZT} (20 mA). See [MicroNote 202](#) for typical Zener Impedance variation with different operating currents.
4. Allowance has been made for the increase in V_Z due to Z_Z and for the increase in junction temperature as the unit approaches thermal equilibrium at the power dissipation of 400 mW.

GRAPHS

FIGURE 1
Temperature-Power Derating Curve

FIGURE 2
Temperature-Power Derating Curve

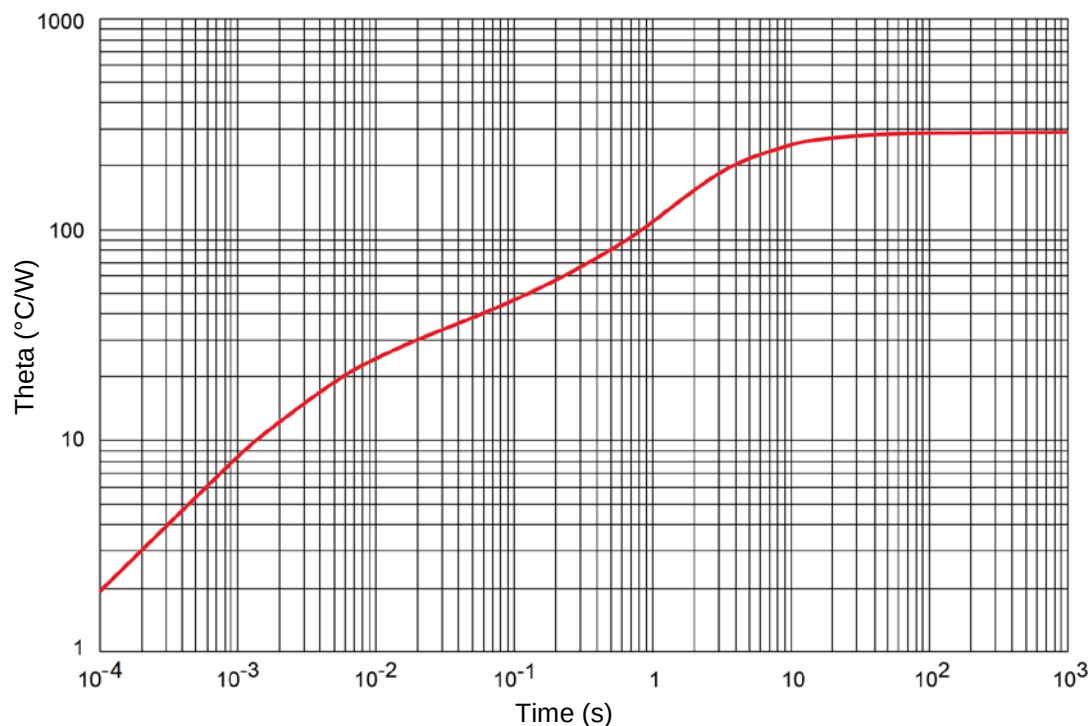
GRAPHS (continued)


FIGURE 3
Thermal Impedance PCB mount

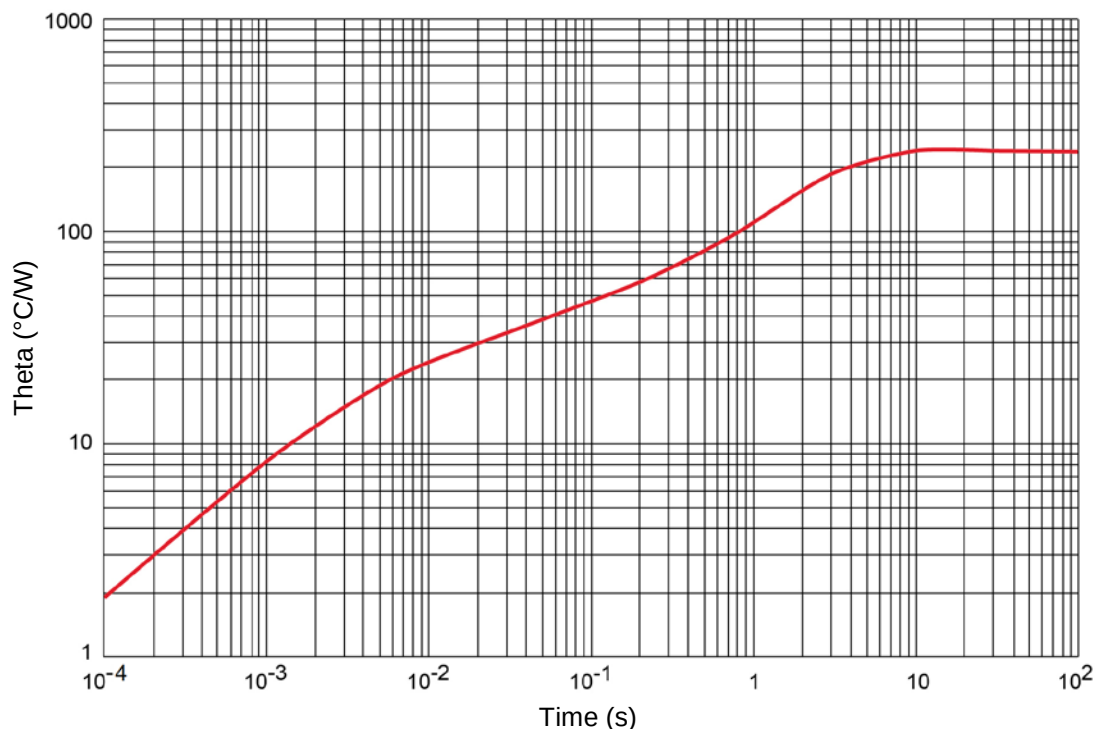
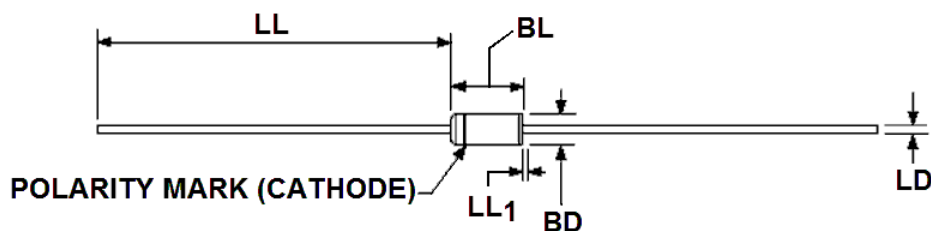


FIGURE 4
Thermal Impedance
($T_L = 25^\circ\text{C}$ at 0.375 inch (9.53 mm) from body.)

PACKAGE DIMENSIONS


Ltr	Dimensions				Notes
	Inch		Millimeters		
	Min	Max	Min	Max	
BD	0.055	0.090	1.40	2.29	3
BL	0.120	0.200	3.05	5.08	4
LD	0.018	0.023	0.46	0.58	
LL	1.000	1.500	25.40	38.10	
LL ₁	-	0.050	-	1.27	5

NOTES:

1. Dimensions are in inches.
2. Millimeters are given for information only.
3. Dimension BD shall be measured at the largest diameter.
4. The BL dimension shall include the entire body including slugs.
5. Dimension LU shall include the sections of the lead over which the diameter is uncontrolled. This uncontrolled area is defined as the zone between the edge of the diode body and extending 0.050 inch (1.27 mm) onto the leads.
6. In accordance with ASME Y14.5M, diameters are equivalent to Φ x symbology.